

# SOT1364-1

plastic, low profile fine-pitch ball grid array package, 97 terminals, 0.65 mm pitch, 8 mm x 8 mm x 1.3 mm body

5 June 2020

Package information

## 1 Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	LFBGA97
<b>Package style descriptive code</b>	LFBGA (low profile fine-pitch ball grid array)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	23-12-2013
<b>Manufacturer package code</b>	SOT1364-1

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	7.9	8	8.1	mm
package width	7.9	8	8.1	mm
seated height	1.2	1.3	1.45	mm
nominal pitch	-	0.65	-	mm
actual quantity of termination	-	97	-	



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2 Package outline

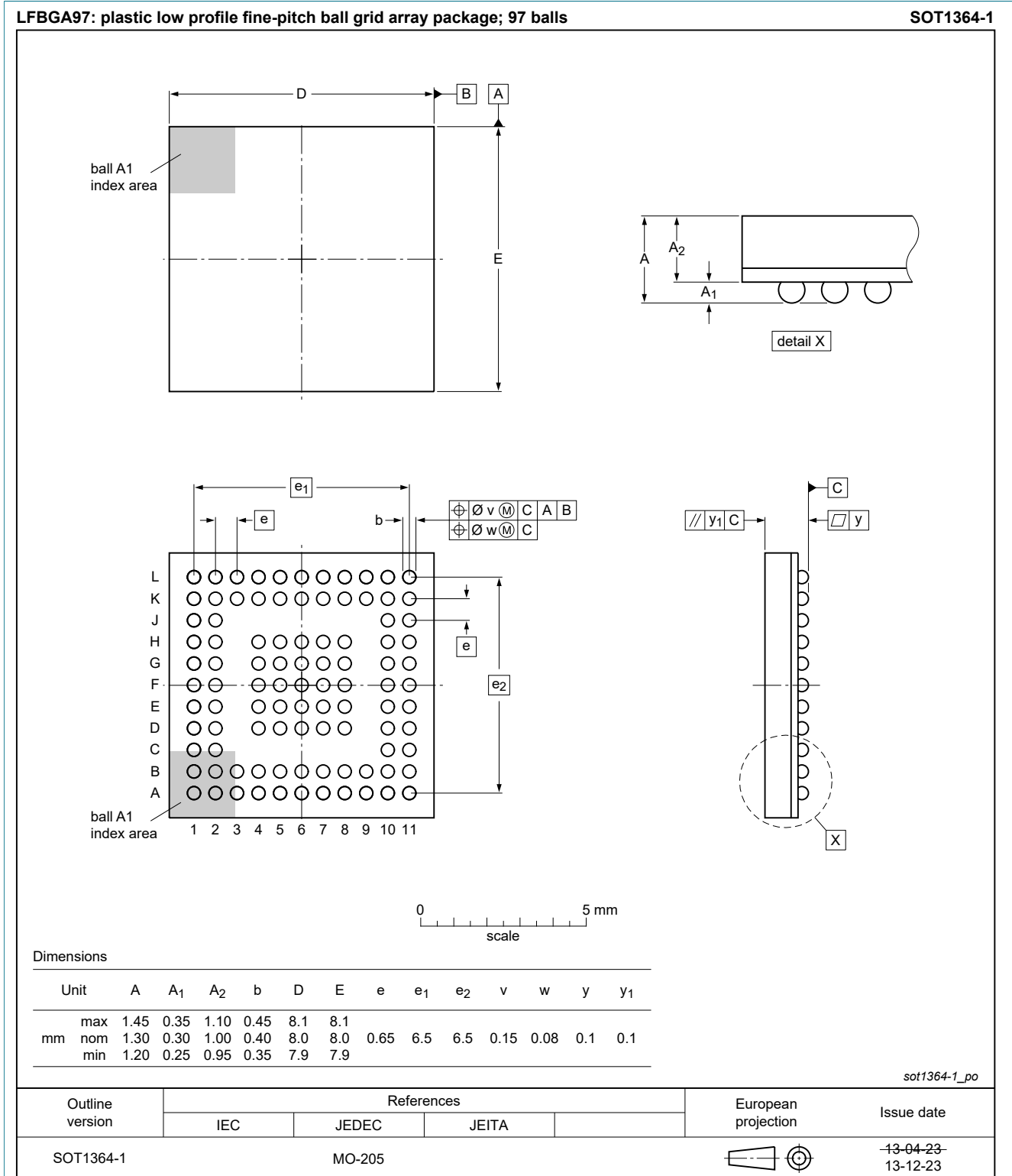


Figure 1. Package outline LFBGA97 (SOT1364-1)

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### 3 Soldering

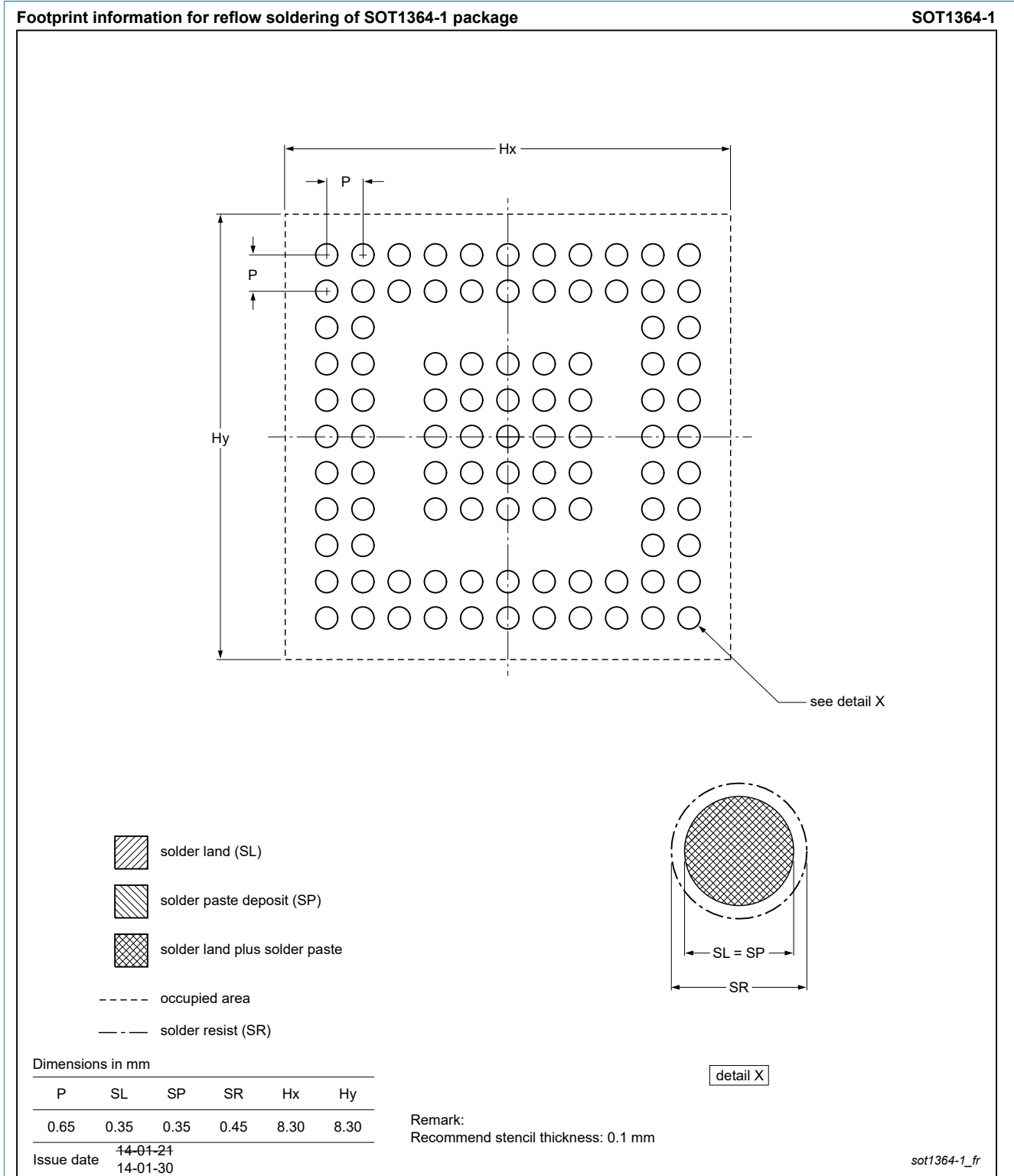


Figure 2. Footprint information for reflow soldering of LFBGA97 (SOT1364-1)

## 4 Legal information

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